

Features

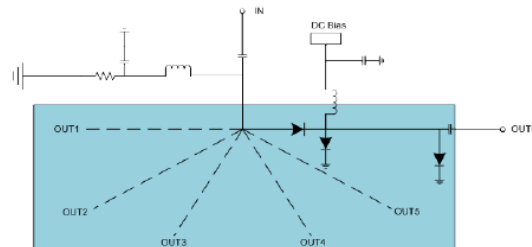
- Frequency: 10-40GHz
- Insertion Loss: 1.3dB typ.
- Isolation: 53dB typ.
- P-1dB: 26dBm
- Input/Output: 50Ω
- Die Size: 2.12x 1.52x 0.1 mm

Typical Applications

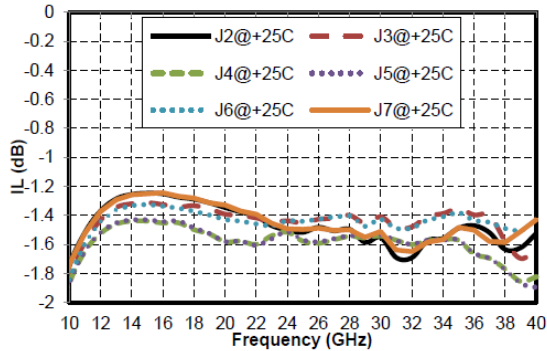
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Electrical Specifications
TA = +25°C

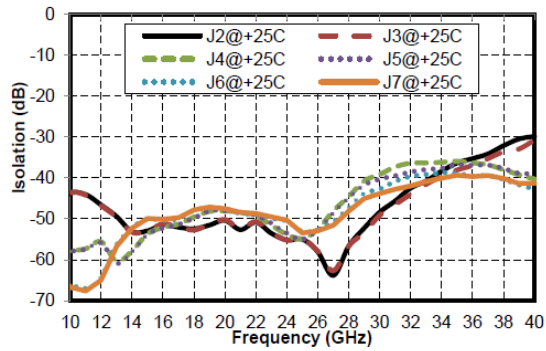
Parameters	Min.	Typ.	Max.	Units
Frequency Range	10-40			GHz
Insertion Loss	-	1.5	1.7	dB
Isolation	36	47	-	dB
Input Return Loss	11	16	-	dB
Output Return Loss	11	15	-	dB
P-1dB	-	26	-	dBm
Switching Speed	-	30	-	ns

Functional Block Diagram


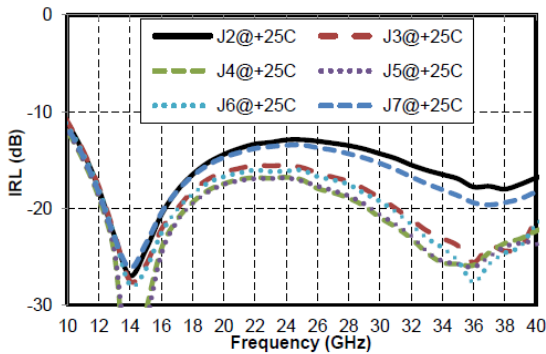
Insertion Loss vs. Operating Frequency



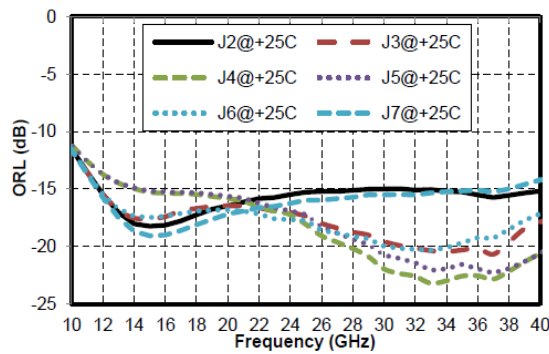
Isolation vs. Operating Frequency



Input Return Loss vs. Operating Frequency



Output Return Loss vs. Operating Frequency



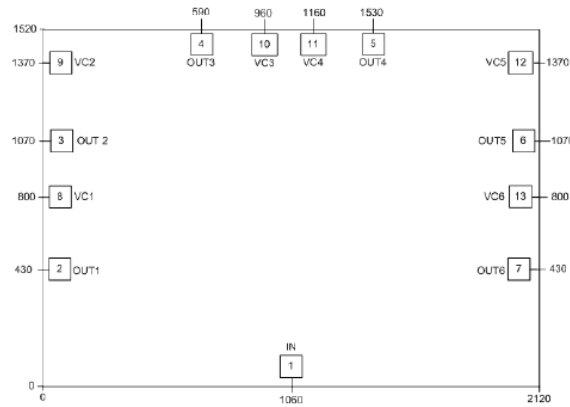
Typical Driver Connections

Control Level (mA)						RF Output State					
VC1	VC2	VC3	VC4	VC5	VC6	J2-J1	J3-J1	J4-J1	J5-J1	J6-J1	J7-J1
-10	10	10	10	10	10	Low Loss	Isolation	Isolation	Isolation	Isolation	Isolation
10	-10	10	10	10	10	Isolation	Low Loss	Isolation	Isolation	Isolation	Isolation
10	10	-10	10	10	10	Isolation	Isolation	Low Loss	Isolation	Isolation	Isolation
10	10	10	-10	10	10	Isolation	Isolation	Isolation	Low Loss	Isolation	Isolation
10	10	10	10	-10	10	Isolation	Isolation	Isolation	Isolation	Low Loss	Isolation
10	10	10	10	10	-10	Isolation	Isolation	Isolation	Isolation	Isolation	Low Loss



Outline Drawing

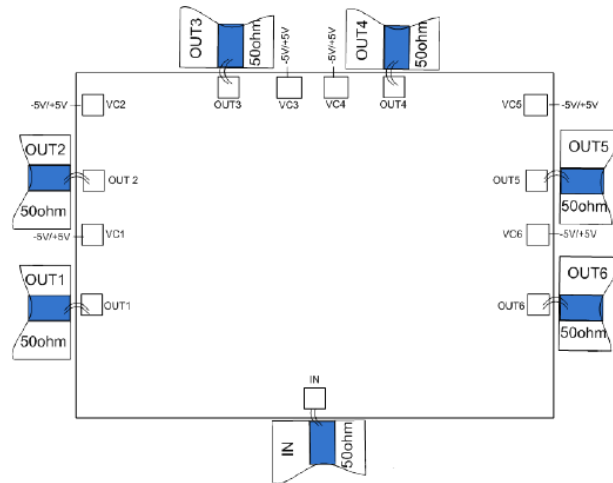
All Dimensions in μm



Pad Description

Pad	Function	Description
1	IN(J1)	RF signal input port
2,3,4,5,6,7	OUT1(J2), OUT2(J3), OUT3(J4), OUT4(J5), OUT5(J6), OUT6(J7)	RF signal output port
8,9,10,11,12,13	VC1,VC2,VC3,VC4,VC5,VC6	Control Port
Die bottom	GND	Die bottom must be connected to RF/DC ground.

Assembly Drawing



Notes:

1. Die thickness: 100 μm
2. Typical bond pad is 100*100 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. Maximum input voltage: 25V
2. Maximum input power: +30dBm CW
3. Operating temperature: -55 $^{\circ}\text{C}$ to +85 $^{\circ}\text{C}$
4. Storage temperature: -65 $^{\circ}\text{C}$ to +150 $^{\circ}\text{C}$